

## ABSTRACT OF THE DISCLOSURE

7 The present invention is directed to a semiconductor chip package  
that can effectively remove heat from a semiconductor chip, and a method  
of fabricating the package. In accordance with an embodiment of the  
invention, the package includes: a substrate having bonding pads; a  
semiconductor chip having conductive bumps on the front side thereof, the  
conductive bump contacting the bonding pads; a heat slug bonded to the  
backside of the semiconductor chip; and a solder film which makes the  
10 bonding between the heat slug and the backside of the semiconductor chip.  
The heat slug can be shaped such that a portion of the heat slug is  
attached to the substrate by an adhesive. The method includes: preparing  
a semiconductor chip having conductive bumps on the front surface of the  
semiconductor chip; bonding a heat slug on the backside of the  
15 semiconductor chip using a solder film; and attaching the semiconductor  
chip on the substrate such that the conductive bumps of the semiconductor  
chip contacts bonding pads of the substrate.